

MANUFACTURING

ELECTRONIC ENCLOSURES

Mentis has designed electronics enclosures for various applications. Designs have included frameworks to fit within geometrical packing constraints, enclosure penetrations for connectors or antennas, environmental seal, and thermal management. We employ rapid manufacturing techniques to produce prototype electronics packages for testing.

KEY FEATURES

- Electronics enclosure for airborne application
- Included 20+ components including fiber optics
- Included 5+ antennas and 8+ bulkhead connectors
- Used ventilation fan with active bulkhead doors

